



Material Content Data Sheet



Sales Product Name	TLE4269GM			Issued	29. August 2013			
MA#	MA000969912							
Package	PG-DSO-14-30			Weight*	143.20 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.966	2.07	2.07	20709	20709
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		421	
	non noble metal	iron	7439-89-6	1.207	0.84		8428	
wire	non noble metal	copper	7440-50-8	49.007	34.22	35.11	342219	351173
	noble metal	gold	7440-57-5	0.266	0.19	0.19	1860	1860
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1201
plastics	plastics	epoxy resin	-	7.911	5.52		55243	
	inorganic material	silicondioxide	60676-86-0	77.906	54.41	60.05	544024	600468
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8562	8562
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7191	7191
glue	plastics	acrylic resin	-	0.316	0.22		2208	
	noble metal	silver	7440-22-4	1.121	0.78	1.00	7829	10037
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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